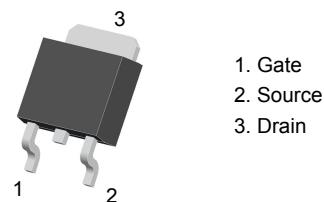


-20V P-Channel Mosfet

FEATURES

- V_{DSS}=-20V, I_D=-60A
R_{DSON} < 8.5mΩ @ V_{GS} = -4.5V
R_{DSON} < 12mΩ @ V_{GS} = -2.5V
- High Power and Current Handling Capability
- Lead Free Product is Acquired
- Surface Mount Package

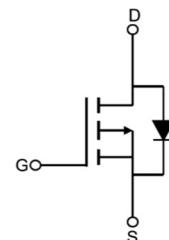
TO-252



APPLICATIONS

- Motor Control and Drive
- Uninterruptible Power Supply (UPS)
- Battery Management

P-CHANNEL MOSFET



Absolute Maximum Ratings(TC=25°C unless otherwise noted)

Symbol	Parameter		Max.	Units
V _{DSS}	Drain-Source Voltage		-20	V
V _{GSS}	Gate-Source Voltage		±12	V
I _D	Continuous Drain Current	T _C = 25°C	-60	A
		T _C = 100°C	-39	
I _{DM}	Pulsed Drain Current ^{note1}		-240	A
P _D	Power Dissipation	T _C = 25°C	70	W
R _{θJC}	Thermal Resistance, Junction to Ambient		2.1	°C/W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C

MOSFET ELECTRICAL CHARACTERISTICS $T_J=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristics						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D = -250\mu\text{A}$	-20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -20\text{V}, V_{GS} = 0\text{V}$,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 12\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-0.35	-0.65	-1.0	V
$R_{DS(\text{on})}$	Static Drain-Source on-Resistance note3	$V_{GS} = -4.5\text{V}, I_D = -15\text{A}$	-	6.6	8.5	$\text{m}\Omega$
		$V_{GS} = -2.5\text{V}, I_D = -12\text{A}$	-	8	12	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = -10\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	-	4590	-	pF
C_{oss}	Output Capacitance		-	505	-	pF
C_{rss}	Reverse Transfer Capacitance		-	440	-	pF
Q_g	Total Gate Charge	$V_{DS} = -10\text{V}, I_D = -15\text{A}, V_{GS} = -4.5\text{V}$	-	46	-	nC
Q_{gs}	Gate-Source Charge		-	7.3	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	10	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -10\text{V}, I_D = -14\text{A}, R_{\text{GEN}} = 2.7\Omega, V_{GS} = -10\text{V}$	-	8	-	ns
t_r	Turn-on Rise Time		-	59	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	111	-	ns
t_f	Turn-off Fall Time		-	43	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	-60	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-240	-	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_s = -20\text{A}$	-	-	-1.2	V
trr	Reverse Recovery Time	$T_J = 25^\circ\text{C}, I_{SD} = -15\text{A}, V_{GS} = 0\text{V}, di/dt = -100\text{A}/\mu\text{s}$	-	18	-	ns
Qrr	Reverse Recovery Charge		-	7.7	-	nC

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

- 2 . EAS condition: $T_J=25^\circ\text{C}, V_{DD}=-10\text{V}, V_G=-10\text{V}, R_G=5.9\Omega, L=0.5\text{mh}, I_{AS}=-13.2\text{A}$
- 3 . Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

TYPICAL PERFORMANCE CHARACTERISTICS

Figure 1: Output Characteristics

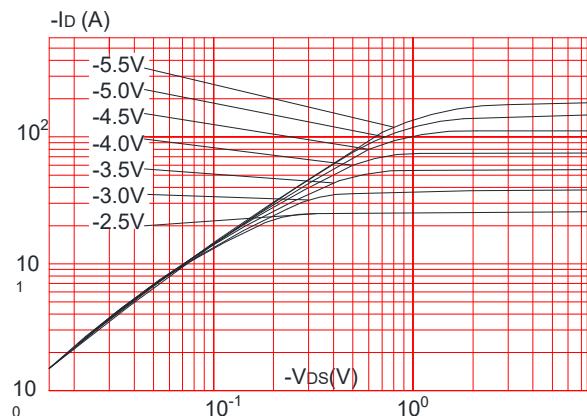


Figure 3: On-resistance vs. Drain Current

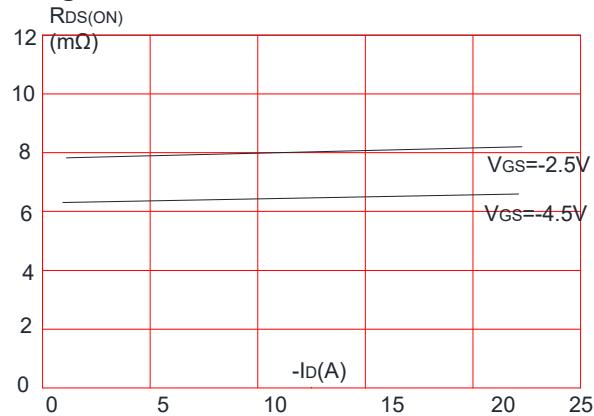


Figure 5: Gate Charge Characteristics

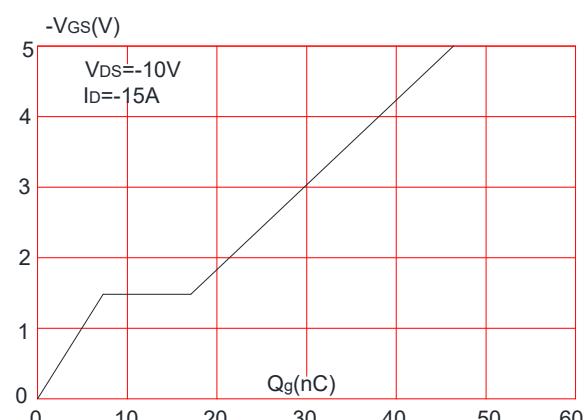


Figure 2: Typical Transfer Characteristics

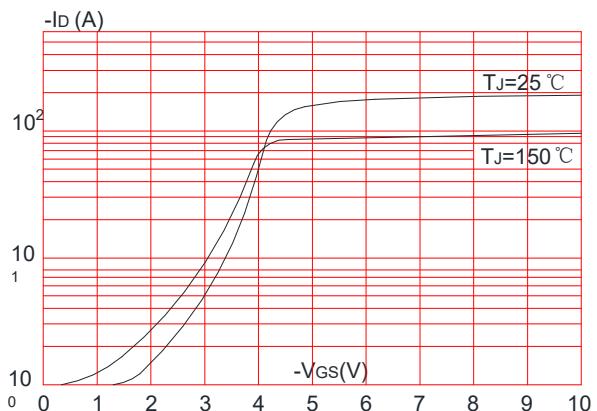


Figure 4: Body Diode Characteristics

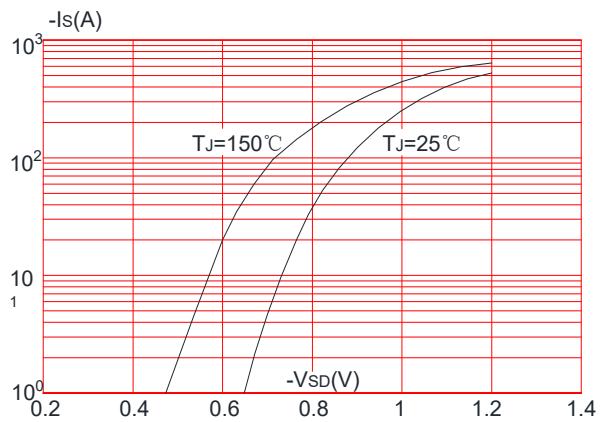
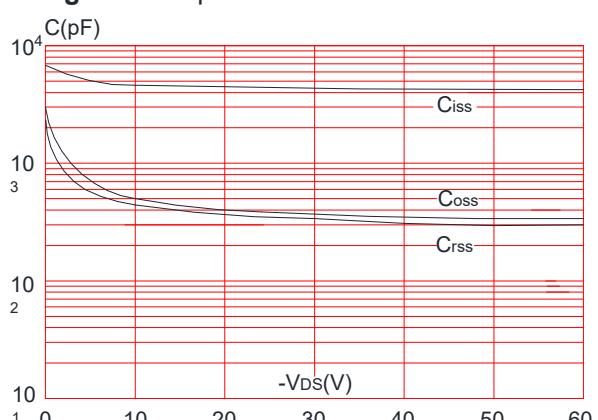


Figure 6: Capacitance Characteristics



TYPICAL PERFORMANCE CHARACTERISTICS (cont.)

Figure 7: Normalized Breakdown Voltage vs.=Junction Temperature

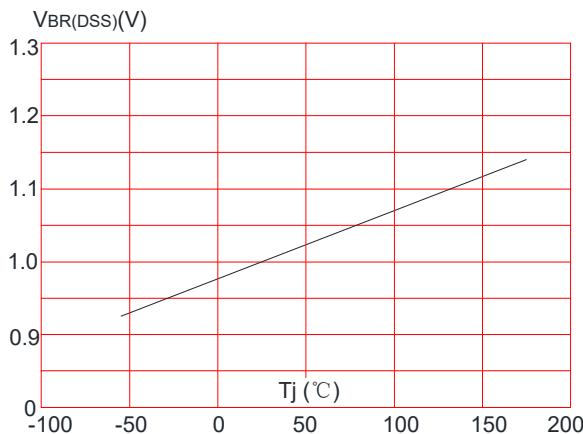


Figure 9: Maximum Safe Operating Area

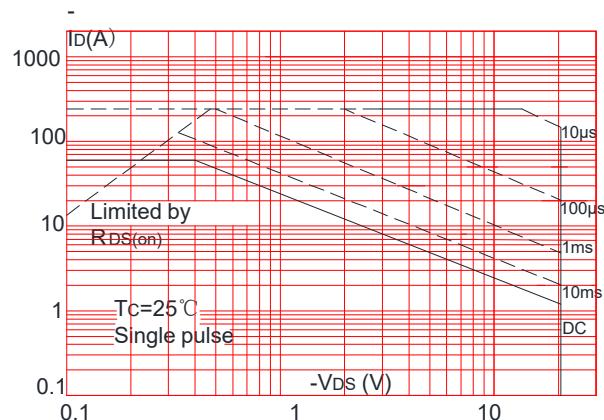


Figure.11: Maximum Effective Transient= Thermal Impedance, Junction-to-Case

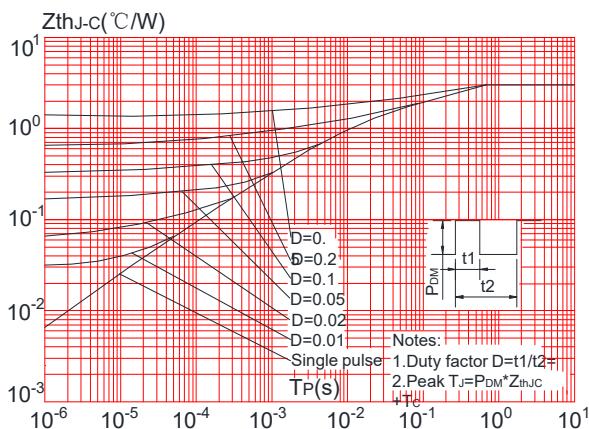


Figure 8: Normalized on Resistance vs.=Junction Temperature

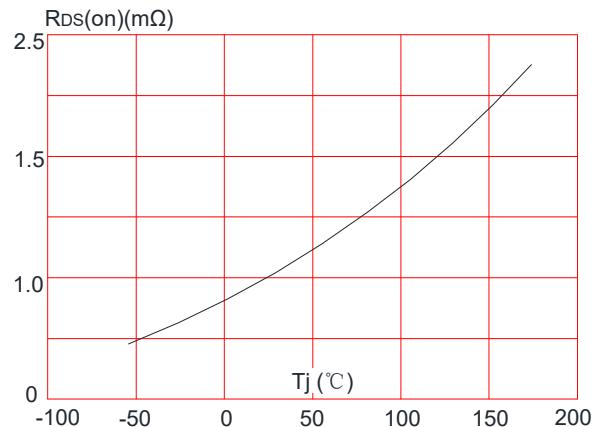
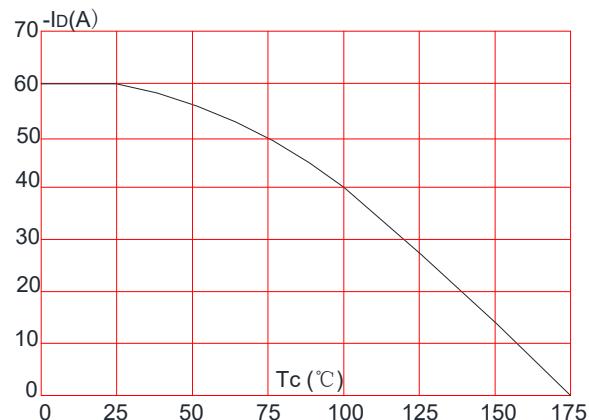
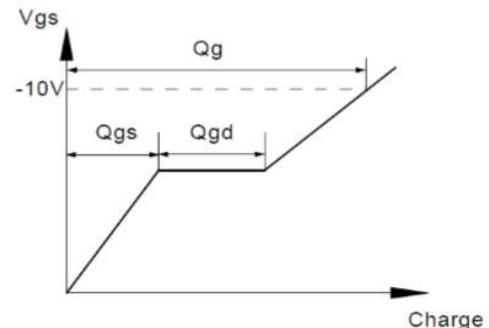
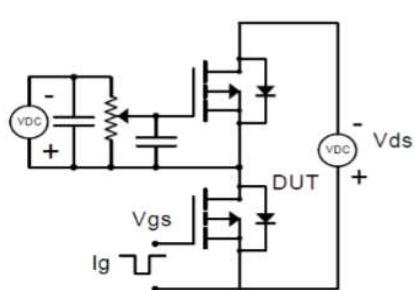


Figure 10: Maximum Continuous Drain Current=vs. Case Temperature

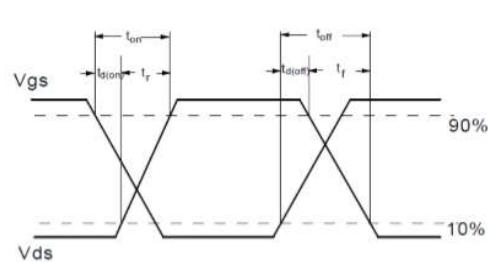
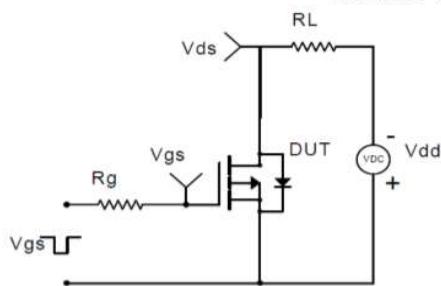


Test Circuit

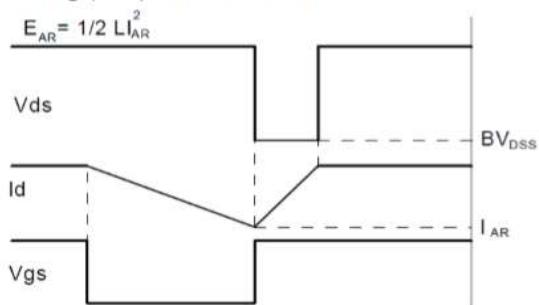
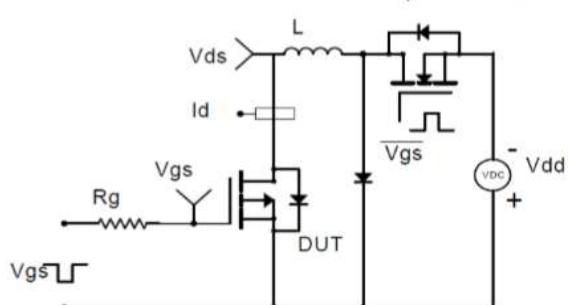
Gate Charge Test Circuit & Waveform



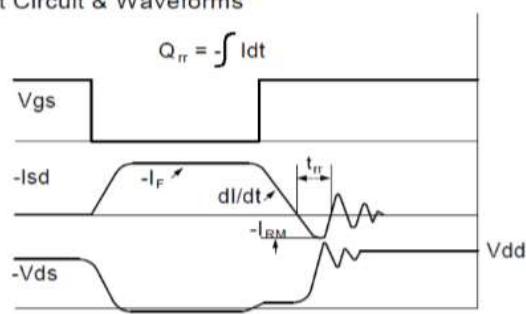
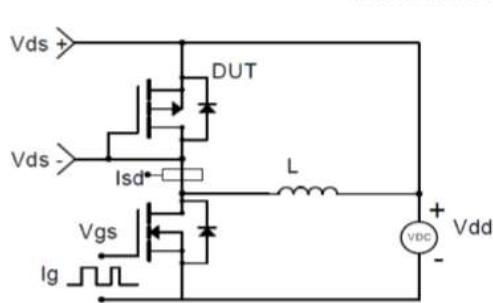
Resistive Switching Test Circuit & Waveforms



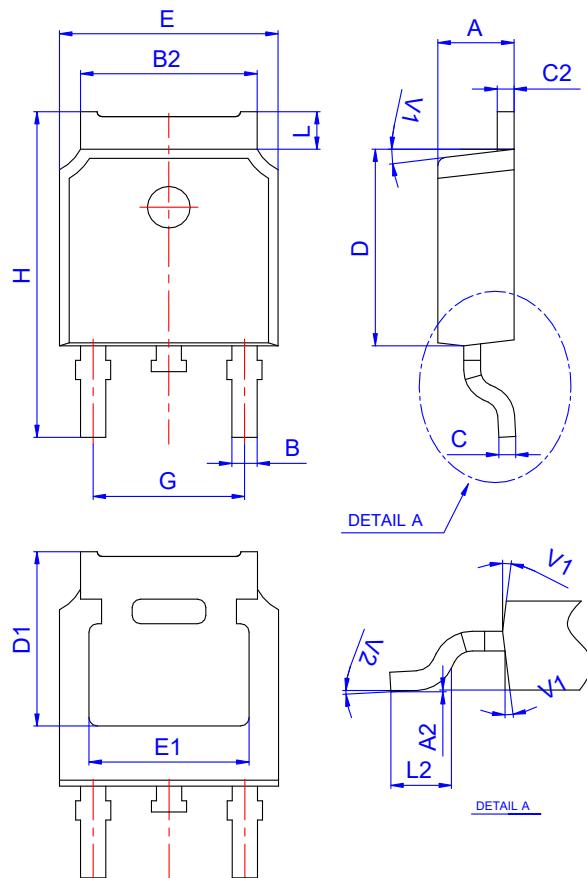
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



TO-252 PACKAGE OUTLINE DRAWING



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°